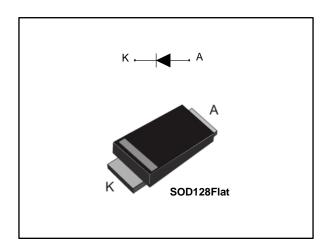


STPS5H100AF

High voltage power Schottky rectifier

Datasheet - production data



Description

This high voltage Schottky barrier rectifier device is packaged in SOD128Flat and designed for high frequency miniature switched mode power supplies and for board DC to DC converters.

Table 1: Device summary

| Symbol | Value |
|-----------------------|--------|
| I _{F(AV)} | 5 A |
| V_{RRM} | 100 V |
| T _i (max.) | 175 °C |
| V _F (typ.) | 0.51 V |

Features

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche specification
- ECOPACK® compliant component

Characteristics STPS5H100AF

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

| Symbol | Pa | Value | Unit | |
|--------------------|---------------------------------------------------------------------------|----------------------------------------------|-------------|----|
| V _{RRM} | Repetitive peak reverse voltage | | 100 | V |
| I _{F(AV)} | Average forward current | T_L = 115 °C, δ = 0.5, square pulse | 5 | Α |
| 1 | Surge non repetitive forward $t_p = 10 \text{ ms sinusoidal}$ | | 125 | ^ |
| IFSM | Current | t _p = 8.3 ms sinusoidal | 130 | Α |
| P _{ARM} | Repetitive peak avalanche power $t_p = 10 \ \mu s, T_j = 125 \ ^{\circ}C$ | | 165 | W |
| T _{stg} | Storage temperature range | | -65 to +175 | °C |
| Tj | Maximum operating junction temperature ⁽¹⁾ | | 175 | °C |

Notes:

Table 3: Thermal parameters

| Symbol | Parameter | Max. value | Unit |
|----------------------|------------------|------------|------|
| R _{th(j-l)} | Junction to lead | 16 | °C/W |

Table 4: Static electrical characteristics

| Symbol | Parameter | Test conditions | | Min. | Тур. | Max. | Unit |
|-------------------------------|-------------------------|-------------------------|------------------------|------|------|------|------|
| | | T _j = 25 °C | V _R = 100 V | - | 0.7 | 3.5 | μΑ |
| I _R ⁽¹⁾ | Reverse leakage current | T _j = 125 °C | | - | 1 | 4 | mA |
| | | T _j = 150 °C | | - | | 16 | |
| V _F ⁽²⁾ | Forward voltage drop | T _j = 25 °C | I _F = 2.5 A | - | | 0.67 | V |
| | | T _j = 125 °C | | - | 0.51 | 0.55 | |
| | | T _j = 25 °C | I _F = 5 A | - | | 0.76 | |
| | | T _j = 125 °C | | - | 0.57 | 0.61 | |

Notes:

To evaluate the conduction losses use the following equation:

 $P = 0.49 \text{ x } I_{F(AV)} + 0.024 \text{ x } I_{F^2(RMS)}$

For more information, please refer to the following application notes related to the power losses.

- AN604 (Calculation of conduction losses in a power rectifier)
- AN4021 (Calculation of reverse losses in a power diode)

 $^{^{(1)}(}dP_{tot}/dT_j) < (1/R_{th(j\text{-}a)}) \text{ condition to avoid thermal runaway for a diode on its own heatsink.}$

⁽¹⁾Pulse test: t_p = 5 ms, δ < 2%

⁽²⁾ Pulse test: t_p = 380 μs, δ < 2%

STPS5H100AF Characteristics

1.1 Characteristics (curves)

1

0

0

Figure 2: Average forward current versus ambient temperature ($\delta = 0.5$) I_{F(AV)}(A) 12 10 T_{amb}(°C) $\delta = tp/T$ 0 50 75 0 25 100 125 150 175

Figure 3: Normalized avalanche power derating versus pulse duration

3

2

 $I_{F(AV)}(A)$

4

 $\delta = tp/T$

5

6

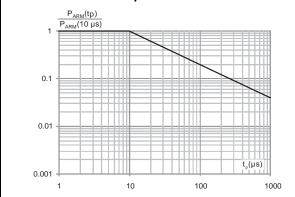


Figure 4: Relative variation of thermal impedance junction to lead versus pulse duration

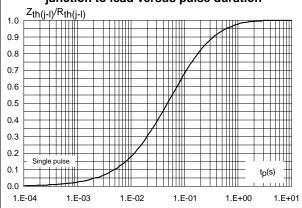


Figure 5: Reverse leakage current versus reverse voltage applied (typical values)

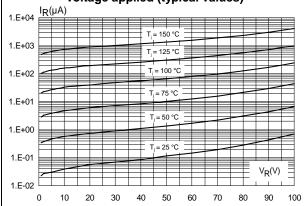
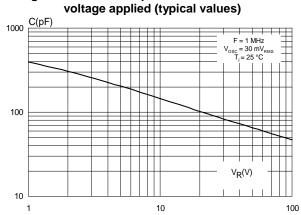


Figure 6: Junction capacitance versus reverse



Characteristics STPS5H100AF

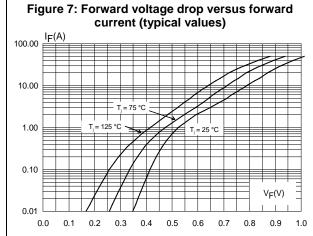


Figure 8: Thermal resistance junction to ambient versus copper surface under each lead (typical values, epoxy printed board FR4, $e_{Cu} = 35 \mu m$) R_{th(j-a)}(°C/W) 200 SOD128-Flat 150 100 50 $S_{\text{Cu}}(\text{cm}^{2})$ 0 0.5 2.5 3.0 3.5 0.0 1.0 1.5 2.0 4.0 4.5 5.0

STPS5H100AF Package information

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Lead-free package

2.1 SOD128Flat package information

E E1

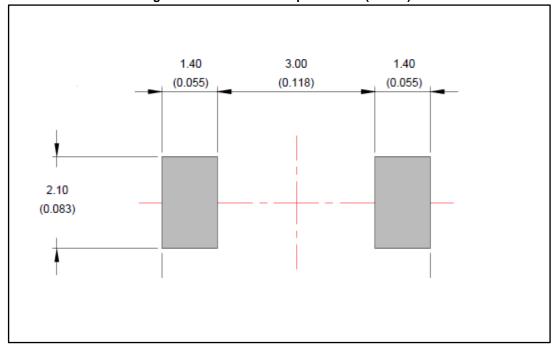
Figure 9: SOD128Flat package outline

b 2x

Table 5: SOD128Flat package mechanical data

| | Dimensions | | | |
|------|-------------|------|-------|--------|
| Ref. | Millimeters | | Inc | hes |
| | Min. | Max. | Min. | Max. |
| А | 0.93 | 1.03 | 0.037 | 0.041 |
| b | 1.69 | 1.81 | 0.067 | 0.071 |
| С | 0.10 | 0.22 | 0.004 | 0.009 |
| D | 2.30 | 2.50 | 0.091 | 0.098 |
| Е | 4.60 | 4.80 | 0.181 | 0.189 |
| E1 | 3.70 | 3.90 | 0.146 | 0.154 |
| L | 0.55 | 0.85 | 0.026 | 0.033 |
| L1 | 0.30 typ. | | 0.012 | 2 typ. |
| L2 | 0.45 typ. | | 0.018 | 8 typ. |

Figure 10: SOD128Flat footprint in mm (inches)



STPS5H100AF Ordering information

3 Ordering information

Table 6: Ordering information

| Order code | Marking | Package | Weight | Base qty. | Delivery mode |
|-------------|---------|------------|---------|-----------|---------------|
| STPS5H100AF | 5H100 | SOD128Flat | 26.4 mg | 3000 | Tape and reel |

4 Revision history

Table 7: Document revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 09-Jan-2017 | 1 | Initial release. |

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